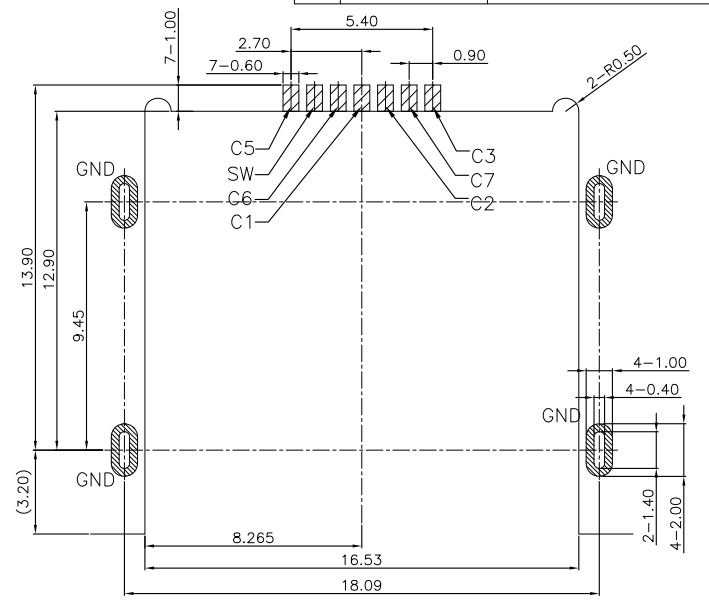
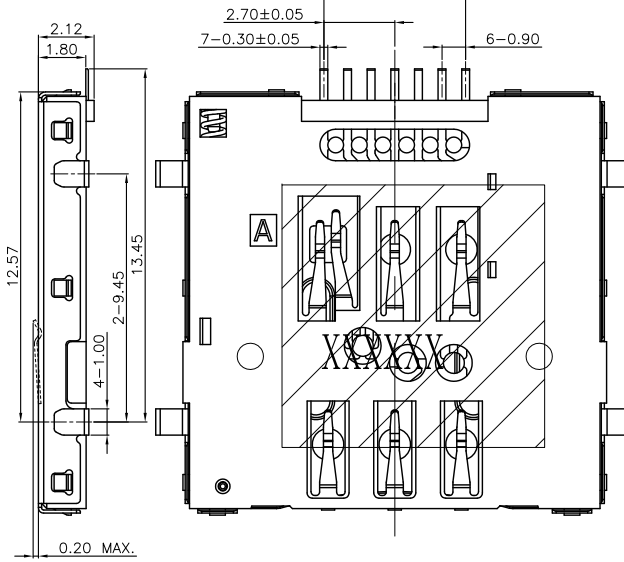
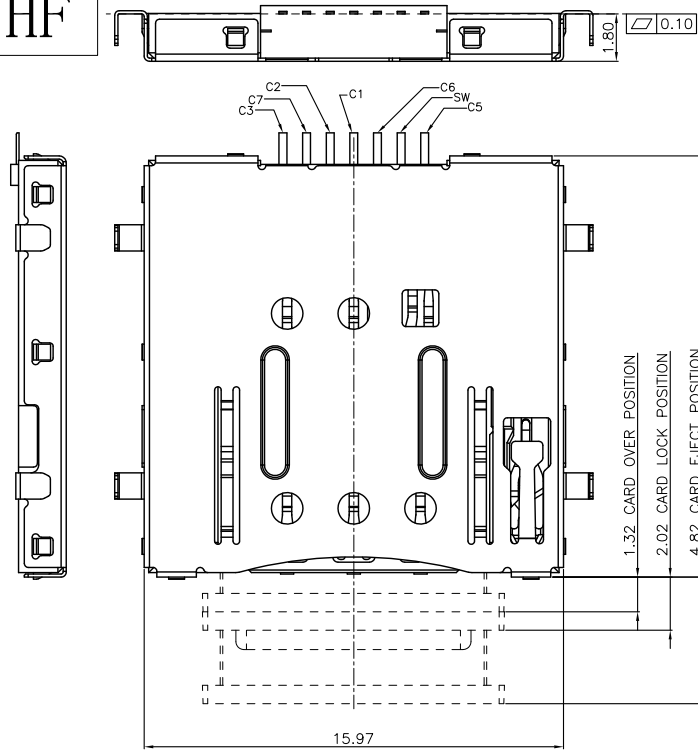


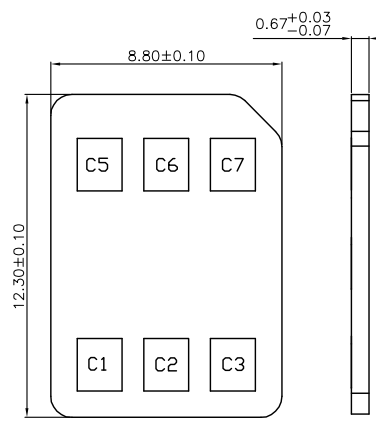
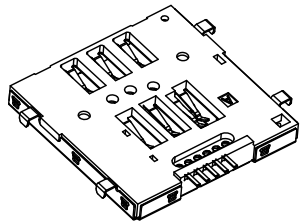
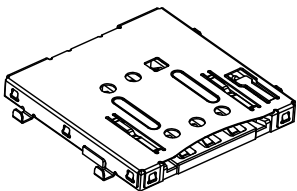
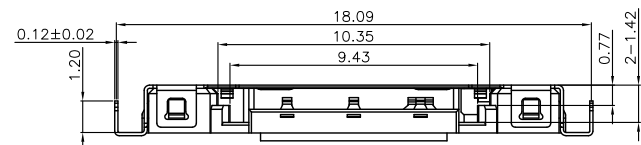
HF

REV.	ECN.NO.	MODIFY.CONTENT



RECOMMEND P.C.B LAYOUT(TOP VIEW)
(General tolerance ±0.05)

▨ PAD AREA



SIM CARD LAYOUT

NOTES:

1. Material
 - 1-1. CONTACT: PHOSPHOR BRONZE C5210 R-EH T=0.10±0.01mm. GOLD PLATING ON CONTACT AREA, MATTE TIN 80u"MIN ON SOLDER TAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - 1-2. SHELL: STAINLESS STEEL SUS304 R-1/2H T=0.12±0.01. 30u" MIN NICKEL PLATING OVERALL.
 - 1-3. HOUSING: LCP S475 BLACK COLOR.
2. ELECTRICAL REQUIREMENTS:
 - 2-1. CURRENT RATING: 0.5A PER PIN.
 - 2-2. CONTACT RESISTANCE: 50mΩ MAX.
 - 2-3. INSULATION RESISTANCE: 100MΩ MIN. 200VDC FOR 1 MINUTE.
 - 2-4. WITHSTANDING STRENGTH: 500V AC FOR 1 MINUTE.
3. MECHANICAL REQUIREMENTS:
 - DURABILITY: 3,000 CYCLES MIN.
4. ENVIRONMENT REQUIREMENTS:
 - 4-1. OPERATING TEMP: -30°C TO +85°C
 - 4-2. STORAGE TEMPERATURE: -40°C TO +85°C
5. RECOMMENDED PROCESS CONDITION:
 - IR-REFLOW, PEAK TEMPERATURE AND TIME: 250°C, 5~10S.
6. PART MUST COMPLY TAI SOL HF WD-3-1-091 SPECIFICATION.

PART NO.:

SP149-AP401-**-**YR

- 42: 功能区镀金1U", 锡脚镀纯锡至少80U"
- 43: 功能区镀金3U", 锡脚镀纯锡至少80U"
- 44: 功能区镀金5U", 锡脚镀纯锡至少80U"
- 45: 功能区镀金10U", 锡脚镀纯锡至少80U"
- 46: 功能区镀金15U", 锡脚镀纯锡至少80U"
- 47: 功能区镀金30U", 锡脚镀纯锡至少80U"

SIM Card Pin Assignments

COMPOSITION OF DETECTION	NANO SIM CARD	
	C1	Vcc
C2	RST	
C3	CLK	
C5	GND	
SW	CD/SW	
C6	Vpp	
C7	DATA	

GENERAL TOLERANCE		DWG.NO.	SP149-AP401-00	PART.NO.	SP149-AP401-**-**	DRAWN	L. M. J 2019. 08. 02	UNIT	mm	SCALE	NO SCALE
x. ±0.50	x. °± 5°	REV.	A	TITLE	Nano SIM Push with tray反向沉板1.80	CHECKED		东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x ±0.25	.x °± 2°	SIZE	A4	SHEET	1/2	APPROVED					
.xx ±0.15	.xx °± 1°	A4									

OLN 东莞市欧联电子科技有限公司
DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.